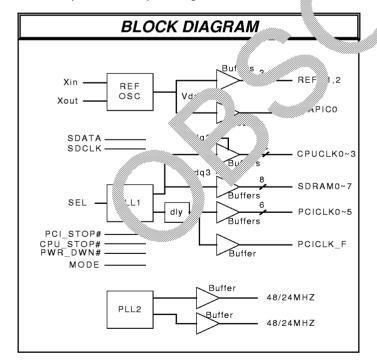


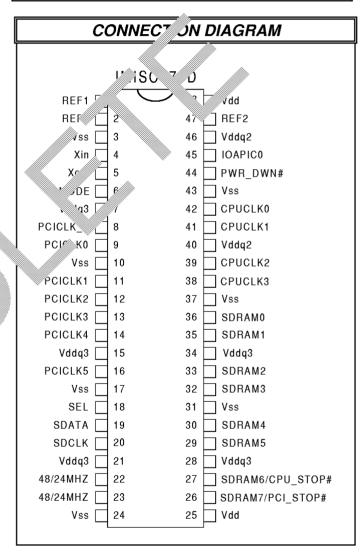
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PRODUCT FEATURES

- Supports Pentium[®] & Pro CPUs.
- 4 CPU clocks up to 8 loads.
- Up to 8 SDRAM clocks for 2 DIMs.
- Supports Power Savings Frequencies.
- 7 PCI synchronous clocks.
- Optional common or mixed supply mode:
- (Vdd = Vddq3 = Vddq2 = 3.3V) or
- (Vdd = Vddg3 = 3.3V, Vddg2 = 2.5V)
- < 250ps skew CPU and SDRAM clocks.
- < 250ps skew among PCI clocks.
- I²C 2-Wire serial interface
- Programmable registers featuring:
 - enable/disable each output pin
 - mode as tri-state, test, or normal
 - 24/48 MHz selections
- 1 IOAPIC clock for multiprocessor support.
- 48-pin SSOP package



FREQUENCY TABLE						
SEL	CPU	PCI				
0	60.0	30.0				
1	66.6	33.3				



Purchase of I^2C components of International Microcircuits, Inc. or one of its sublicensed Associated Companies conveys a license under the Philips I^2C Patent Rights to use these components in an I^2C system, provided that the system conforms to the I^2C Standard Specification as defined by Philips.





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PIN DESCRIPTION

Xin, Xout - These pins form an on-chip reference oscillator when connected to terminals of an external parallel resonant crystal (nominally 14.318 MHz). Xin may also serve as input for an externally generated reference signal.

SEL - Standard frequency select input. It has internal pull-up.

CPUCLK(0:3) - Low skew (<250 pS) clock outputs for host frequencies such as CPU, Chipset, Cache. Vddq2 is the supply voltage for these outputs.

SDRAM(0:5) - Synchronous DRAM DIMs clocks. They are powered by Vddq3.

SDRAM6/CPU_STOP# - If MODE=1, this pir Synchronous DRAM DIMs clock output powered by Vddq3. If MODE=0, this pin is a CPU_ST_P# input signal, where a low level stops the CPU however, the SDRAM clocks will stay active. It has a integral pullup.

SDRAM7/PCI_STOP# - If MODL 1 in pin is a Synchronous DRAM DIMS in k output powed by Vddq3. If MODE=0, this pin is a PC ST if input signal, where a low lever stops in CI clocks except the PCI_F. It has an interview -up.

MODE - A low vel on a pine a ses pins 26, and 27 to be power nanageme inputs PCI_STOP#, and CPU_STOP# spectly. A gh level on this pin causes pins 26, and 2 to be clock output signals SDRAM7, and SDRAM6 reactive.

PCICLK(0:5) - Low skew (<250pS) clock outputs for PCI frequencies. These buffers voltage level is controlled by Vddq3

PCICLK_F - A PCI clock sutput that does not stop until in power down mode. As synchronous with other PCI clocks.

REF(0:2) - B erea puts of 4.3 MHz on-chip reference.

IOAPICO - E fered output of 14.3MHZ for multiplecessor support. It is powered by Vddq2.

WR_D' \# - Power down pin. When this pin is as ort low, the IC is in shutdown mode where all circular is turned off including VCO, crystal buffer and PCICL. Fint has an internal pull-up. The I²C interface is disable, with the PWR_DWN# pin is low.

18// **MHz(0:1)** - Programmable 48 MHZ or 24 MHZ ock outputs.

SDATA - serial data of I²C 2-wire control interface. Has internal pull-up resistor.

SDCLK - serial clock of I²C 2-wire control interface. Has internal pull-up resistor.

Vss - Ground pins for the chip.

Vdd - 3.3 Volt power supply pins for analog circuit and core logic.

Vddq3 - Power supply pins for 3.3V IO pins.

Vddq2 - Power supply pins for 2.5V/3.3V IO pins.



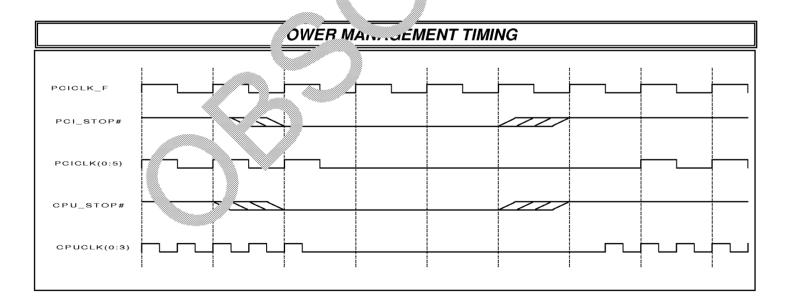
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POWER MANAGEMENT FUNCTIONS

All clocks can be individually enabled or stopped via the 2-wire control interface. All clocks are stopped in the low state. All clocks maintain a valid high period on transitions from running to stopped and on transitions from stopped to running when the chip was not powered down. On power up, the VCOs will stabilize to the correct pulse widths within about 0.2 mS. The CPU, SDRAM, and PCI clocks transition between running and stopped by waiting for one positive edge on PCICLK_F followed by a negative edge on the clock of interest, after which high levels of the output are either enabled or disabled.

When MODE=0, pins 26 and 27 are inputs PCI_STOP# and CPU_STOP# respectively frien MC_E=1, these functions are not available). A particular output is enabled only when both the serial interface and trace is indicate that it should be enabled. The IMISC671 clocks may be disabled according to the following table order reduce power consumption. All clocks are stopped in the low state. All clocks maintain a validing the period of trace it into stopped. On low to high transitions of PWR_DWN#, external circuitry should alique 0.2 mS for the VCOs to stabilize prior to assuming the clock periods are correct. The CPU and PCI clocks transition at tween running and stopped by waiting for one positive edge on PCICLK_F followed by a negative edge on the clock of lighter which high levels of the output are either enabled or disabled.

CPU_STOP#	PCI_STOP#	PWR_DWN#	CPUCLK	F. LK	/_HER CLKs	XTAL & VCOs
Х	Х	0	LOW	LOV	LOW	OFF
0	0	1	LOV	LOW	RUNNING	RUNNING
0	1	1	LOW	33/30 **HZ	RUNNING	RUNNING
1	0	1	'HZ	. W	RUNNING	RUNNING
1	1	1	66/60 Mi 3	€ 30 MHZ	RUNNING	RUNNING





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2-WIRE L'C CONTROL INTERFACE

The 2-wire control interface implements a write only slave interface. The IMISC671D cannot be read back. Sub-addressing is not supported, thus all preceding bytes must be sent in order to change of the control bytes. The 2-wire control interface allows each clock output to be individually enabled or disabled. It is allows 24/48 MHZ frequency selection and test mode enable.

During normal data transfer, the SDATA signal only changes when the DCL, gnal is 16%, and is stable when SDCLK is high. There are two exceptions to this. A high to low transition of SDATA wile SDCLK is high is used to indicate the start of a data transfer cycle. A low to high transition on SDATA wile SDCLK ligh indicates the end of a data transfer cycle. Data is always sent as complete 8-bit bytes, after which a scknowledge is generated. The first byte of a transfer cycle is a 7-bit address with a Read/Write bit as the SB. Data is ansferred MSB first.

The device will respond to writes to 10 bytes (max) of a to a ress <u>D2</u> by generating the acknowledge (low) signal on the SDATA wire following reception of each byte. The level will not respond to any other control interface conditions. The I²C interface is disabled when the PWR DWN# pin level.

SERIAL CONTOC RECISTERS

NOTE: The Pin# column lists the affecte pin numb where applicable. The @Pup column gives the state at true power up. Bytes are set to the values shown ally on true power up, and not when the PWR_DWN# pin is activated.

Following the acknowledge of the Add July Byte (D2), two additional bytes must be sent:

- 1) "Command Code " byte, and
- 2) "Byte Count" byte.

Although the data (bit, in the atvo bytes are considered "don't care", they must be sent and will be acknowledged.

Byte 0: Function School it is air or

Bit	@l ıp	Pin#	Description
7	Ú	*	Reserved, Don't set
6	0		Reserved, Don't set
5	0	*	Reserved, Don't set
4	0	*	Reserved, Don't set
3	1	23	48/24 Mhz (See note 1)
2	1	22	48/24 Mhz (See note 1)
1	0		Bit1 Bit0
0	0		1 1 Tri-State
			1 0 Reserved
			0 1 Test Mode
			0 0 Normal

Note 1: Bits 3 and 2 are for selecting the function of pins 23 and 22 respectively. If these bits are set to "1" (default), the outputs will be 48 Mhz. If they are set to "0" the outputs are 24 MHz.

IMPORTANT NOTE

Reserved bits are intended for possible future functions. It is important that they be left at thie Power Up logic levels at all times. Otherwise data sheet specifications cannot be guaranteed.



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SERIAL CONTROL REGISTERS (Cont.)

Function Table

Function		Outputs						
Description	CPU	PCI	SDRAM	Ref	IOAPIC	24MHZ	48MHZ	
Tri-State	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z	
Test Mode	Tclk/2	Tclk/4	Tclk/2	Tclk	Tclk	Tclk/4	⁻/sik/2	
Normal SEL=1	66	CPU/2	CPU	14.318	14.318	24	48	
Normal SEL=0	60	CPU/2	CPU	14.318	14.318	24	48	

Notes:

- 1. Tclk is a test clock over driven on the Xin input during test mode.
- 2. The frequency ratio Fout/Fin for the USB output is 3.35294.

Byte 1: CPU, 48/24 MHz Clock Register (1 = enable, 0 = Stoppe

Bit	@Pup	Pin#	Description
7	1	23	48/24 MHz enable/Stopped
6	1	22	48/24 MHz enat /Stopped
5	х	-	Reserved
4	х	-	Reserve
3	1	38	CPUCI 3 enable/ toppud
2	1	39	CPUC (2 enable/sopped
1	1	41	CDI ICLi enable/ topped
0	1	42	CPUCLK0 e

Byte 2: PCI Clock Register (1 = enable, 0 = Stop ed)

Bit	@Pup	Pin ²	Description
7	х		eserved
6			³ CICLK_F enable/Stopped
5	1	16	PCICLK5 enable/Stopped
4	1	14	PCICLK4 enable/Stopped
3	1	13	PCICLK3 enable/Stopped
2		12	PCICLK2 enable/Stopped
1	1	11	PCICLK1 enable/Stopped
0	1	9	PCICLK0 enable/Stopped



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SERIAL CONTROL REGISTERS(Continued)

Byte 3: SDRAM Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description
7	1	26	SDRAM7 enable/Stopped
6	1	27	SDRAM6 enable/Stopped
5	1	29	SDRAM5 enable/Stopped
4	1	30	SDRAM4 enable/Stopped
3	1	32	SDRAM3 enable/Stopped
2	1	33	SDRAM2 enable/Stopped
1	1	35	SDRAM1 enable/Stopp
0	1	36	SDRAM0 enable/Stoy Jed

Byte 4: Additional SDRAM Clock Register (1 = enable, 0 = Sto, ed)

Bit	@Pup	Pin#	Description
7	Х	-	Reserve
6	Х	-	Rescived
5	Х	-	Res rved
4	Х	-	Res red
3	Х	- ///	neserv 1
2	Х	-	Prred
1	Х	-	Heser ∋d
0	Х	-	Reselved

Byte 5: Peripheral Conti (1 enal.), 0 = Stopped)

Bit	@Pu _b	Nr /	Description		
7	Х	-	Reserved		
6	X	_	Reserved		
5	1	-	Reserved		
4	_	45	IOAPIC0 enable/Stopped		
3	х	-	Reserved		
2	1	47	REF2 enable/Stopped		
1	1	1	REF1 enable/Stopped		
0	1	2	REF0 enable/Stopped		



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SERIAL CONTROL REGISTERS(Continued)

Byte 6: Reserved Register

Bit	@Pup	Pin#	Description	
7	х	-	Reserved	
6	Х	-	Reserved	
5	Х	-	Reserved	
4	Х	-	Reserved	
3	Х	-	Reserved	
2	Х	-	Reserved	
1	Х	-	Reserved	
0	Х	-	Reserved	

Byte 7: Frequency Control

If the three LSBs of this register are 111 (as at power up), the frequency is controlled by the SEL package pin. Note that if this pin is open, the internal princip winterplaced by MHz. Otherwise, the CPU clock frequency is controlled by F_SEL(0:2).

Bit	@Pup	Desc' ption
7	Х	Resei ad
6	Х	₽nserved
5	X	Resirved
4	Х	Re Jive '
3	х	' eserve
2	1	ı SEL.
1	1	F_5 .∟1
0	1	F_SEL0

FSEL2	FSEL1	FSEL0	FREQUENCY
0	0	0	Reserved
0	0	1	Reserved
0	1	0	Reserved
0	1	1	33 MHz
1	0	0	50 MHz
1	0	1	55 MHz
1	1	0	60 MHz
1	1	1	From SEL pin
1 1	0 1 1	1 0 1	55 MHz 60 MHz





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MAXIMUM RATINGS

Voltage Relative to VSS: -0.3V Voltage Relative to VDD: 0.3V Storage Temperature: -65°C to + 150°C Operating Temperature: 0°C to +70°C Maximum Power Supply: 7V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any verage higher than the maximum rated voltages to his which For proper operation, Vin and Vout she is be consumed the range:

SS<(Vin or Jut)<VDD

Unuse inputs mus Iways be tied to an appropriate loc voltage level (eith VSS or VDD).

ELECTRICAL CHARACTL VIST CS								
Characteristic	Symbol	Min	Тур	ı X	Units	Conditions		
Input Low Voltage	VIL	- ,		0.	√dc	-		
Input High Voltage	VIH	2.0	· -	T - \	Vdc	-		
Input Low Current	IIL			,6	μA			
Input High Current	IIH		1	5	μA			
Output Low Voltage	VC	-	Γ.	0.4	Vdc	All Outputs (see buffer spec)		
IOL = 4mA		l	1					
Output High Voltage	1 .'OH	2.4	-	-	Vdc	All Outputs Using 3.3V Power		
IOH = 4mA						(see buffer spec)		
Tri-State leakage Curren	IOZ	-	-	10	μA			
Dynamic Supply C	Idd	-	-	100	mA	CPU = 66.6 MHz, PCI = 33.3 MHz		
Static Supply Carent		-		750	μA	Powered Down = Active		
Short Circuit Carrent	ISC	25	-	-	mA	1 output at a time - 30 seconds		
			VDE) = VDDQ3	3.3V+5%	$0. VDDQ2 = 2.5V \pm 5\%$. TA = 0°C to +70°C		



f²C Clock Generator for Pentium[®] Notebook Designs.

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SWITCHING CHARACTERISTICS							
Characteristic	Symbol	Min	Тур	Max	Units	Conditions	
Output Duty Cycle	-	45	50	55	%	Measured at 1.5V	
CPU to PCI Offset	tOFF	1	-	4	ns	15 pf Load Measured at 1.5V	
Buffer out Skew All CPU and PCI Buffer Outputs	tSKEW	-	-	250	ps	15 r Load Measured at 1.5V	
ΔPeriod Adjacent Cycles	ΔΡ	-	-	<u>+</u> 250	ps	-	
Jitter Spectrum 20 dB Bandwidth from Center	B W J			500	KHz		
Overshoot/Undershoot Beyond Power Rails	V _{over}	-	-	1.5	V	⁷ 2 ohms @ Jurce of 8 inch PCB run to 15 pf load	
Ring Back Exclusion	V _{RBE}	0.7		2.1	V	note1	
	•	-	VDD -	VDDG -		VDDQ2 = 2.5V+5% TA = 0°C to +70°C	

VDD = VDDG -3.3V %, VDDQ2 = 2.5V±5%, TA = 0°C to +70°C

note 1: Ring Back must not enter this range.

TB4LB TYPE BUFFER CHARACTERISTIC FOR CPUC (0:3), IOAPIC AND SDRAM (0:7)						
Characteristic	Symbol	Min	Tvn	ı x	[‡] ⁄aits	Conditions
Pull-Up Current	IOH	22	1	2L	mA	Vout = VDDQ25V
Pull-Up Current	IOH	3	-	56	mA	Vout = 1.25V
Pull-Down Current	IOL	30	-	41	mA	Vout = 0.4V
Pull-Down Current	101	75		102	mA	Vout = 1.2V
Rise/Fall Time Min Between 0.4 V and 2.0 V	TR _{nin}				nS	10 pF Load
Rise/Fall Time Max Between 0.4 V and 2.0	3F _{max}			2.0	nS	20 pF Load
VDD - VDDQ3 -3 3V+5% VDDQ2 - 2 5V+5% TA - 0°C to +70°C						

VDD = VDDQ3 =3.3V ± 5 %, VDDQ2 = 2.5V ± 5 % , TA = 0°C to +70°C

1 35L1 TYF BUFFER CHARACTERISTICS FOR REF(1:2) and 48/24 MHz						
Characteristic	Symbol	Min	Тур	Max	Units	Conditions
Pull-Up Current	IOH	13	-	17	mA	Vout = VDD-0.5V
Pull-Up Current	IOH	30	-	44	mA	Vout 1.5V
Pull-Down Current	IOL	13	-	19	mA	Vout = 0.4V
Pull-Down Current	IOL	32	-	44	mA	Vout = 1.5V
Rise/Fall Time Min Between 0.4 V and 2.4 V	TRF _{min}	1.0	-	-	nS	10 pF Load
Rise/Fall Time Max Between 0.4 V and 2.4 V	TRF _{max}	-	-	2.0	nS	20 pF Load

 $VDD = VDDQ3 = 3.3V \pm 5\%$, $VDDQ2 = 2.5V \pm 5\%$, TA = 0°C to +70°C



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TB4L1 TYPE BUFFER CHARACTERISTICS FOR PCICLK (0:5, F), REF0						
Characteristic	Symbol	Min	Тур	Max	Units	Conditions
Pull-Up Current	IOH	18	-	23	mA	Vout = VDD5V
Pull-Up Current	IOH	44	-	64	mA	Vout = 1.5
Pull-Down Current	IOL	18	-	25	m/	Vout = 0.4
Pull-Down Current	IOL	50	-	70	۱ ۱	Vout = 1.5
Rise/Fall Time Min Between 0.4 V and 2.4 V	TRF _{min}	0.5	-	/	nS	∫ pF Load
Rise/Fall Time Max Between 0.4 V and 2.4 V	TRF _{max}	-	-		nS	30 pF Load

VDD = VDDQ3 =3.3V ±5%, VDD 2 = 2.5V±5%, TA = 0°C to +70°C

	CRYSTAL AND REFERENCE OSC! LATO PARAMETERS							
Characteristic	Symbol	Min	Тур	Max	Units	Conditions		
Frequency	F。	12.00	14.31818	16.00	- U			
Tolerence	TC	-	-	4100	PPM	Calibration note 1		
	TS	ı	-/	+/- ``O	PPM	Stability (Ta -10 to +60C) note 1		
	Τ A	ı		5	PPM	Aging (first year @ 25C) note 1		
Mode	ОМ	-		-		Parallell Resonant		
Pin Capacitance	СР		6		pF	Capacitance of XIN and Xout pins to ground (each)		
DC Bias Voltage	V_{BIAS}	0.3 \ d	vac.)	0.7Vdd	V			
Startup time	Ts		-///	30	μS			
Load Capacitance	Cl		_0	-	pF	the crystals rated load. note 1		
Effective Series resonant resistance	Ri	-	-	40	Ohms			
Power Dissipatio	DL		-	0.10	mW	note 1		
Shunt Capacitan	СО	-		8	pF	crystals internal package capacitance (total)		

For maximum accuracy total circuit loading capacitance should be equal to CL. This loading capacitance is the effective capacitance across the crystal pins and includes the device pin capacitance (CP) in parallel with any circuit traces, the clock generator and any onboard discrete load capacitors.

Budgeting Calculations

Typical trace capacitance, (< half inch) is 4 pF, Load to the crystal is therefore

Clock generator internal pin capacitance of 36 pF, Load to the crystal is therefore

External crystal loading capacitors (connect to ground)

15.0 pF

the total parasitic capacitance would therefore be

2.0 pF

3.0 pF

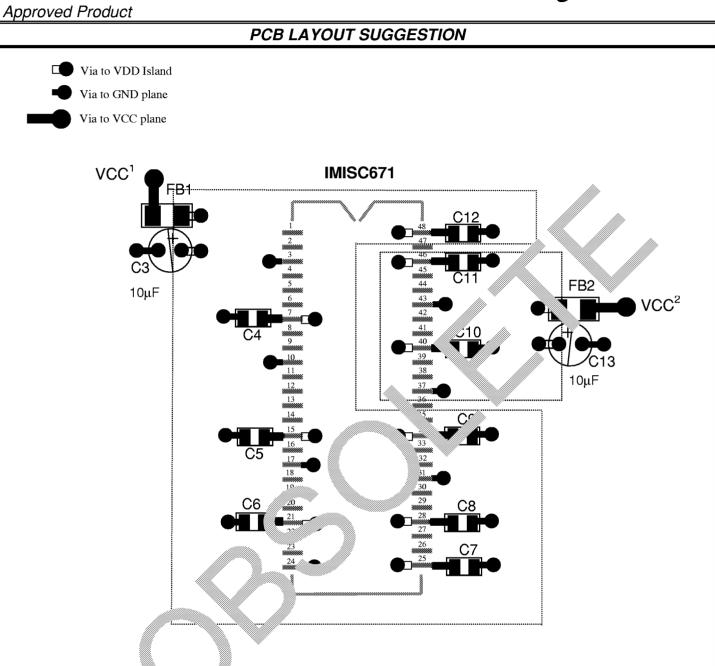
2.0 pF

2.0 pF

2.0 pF

Note 1: It is recommended but not manditory that a crystal meets these specifications.



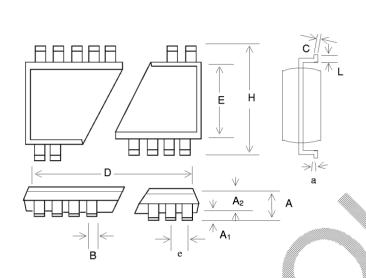


This is only a layout recommendation for best performance and lower EMI. The designer may choose a different approach but C4, C5, C6, C7, C8, C9, C10, C11and C12 (all are $0.1\mu f$) should always be used and placed close to their VDD pins.



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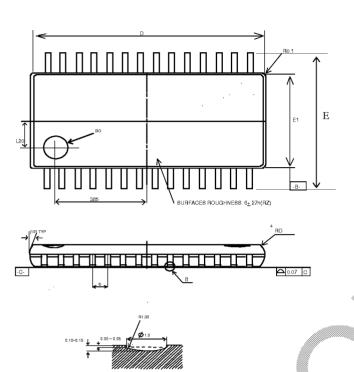
PACKAGE DRAWING AND DIMENSIONS



48 PI	48 PIN SSOP OUTLINE DIMENSIONS								
		INCHE	,	MILLIMETERS					
SYMBOL	MIN	Nº Ji	MAX	MIN	NOM	MAX			
Α	0.095	102	.110	2.41	2.59	2.79			
A ₁	0.0	0.0	0.016	0.20	0.31	0.41			
A2	⁷ . 35	0.090	ົ່ງ	2.16	2.29	2.41			
b	0.00ε	0.010	0.0135	0.203	0.254	0.343			
,	0.005	908	0.010	0.127	0.20	0.254			
D	0.620	0.625	0.637	15.75	15.88	16.18			
П	0.2	0.295	0.299	7.39	7.49	7.59			
		0.0256 BS	C	C	.640 BS	C			
Н	0.395	0.408	0.420	10.03	10.36	10.67			
	0.024	0.030	0.040	0.61	0.76	1.02			
a	O ₅	4º	8₀	0º	4º	8º			

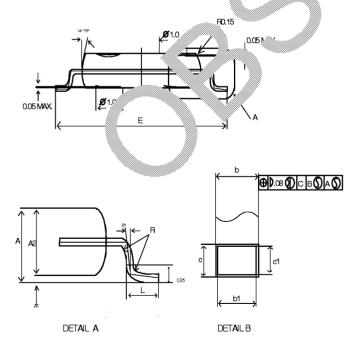


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SECTION V-V

48 PIN TSSOP DIMENSIONS								
		INCHES		MILLIMETERS				
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX		
Α	-		33 ر		-	1.10		
A1	0.00	0.004	റ.006	_{2.05}	0.10	0.15		
A2	్ ,కర	0.035	U.	0.85	0.90	0.95		
L	0.019	`23	0.029	0.50	0.60	0.75		
P	0.043	-		0.10	-	-		
5	J.006	-	0.010	0.170	-	0.27		
þ,	0.006	0.008	0.009	0.170	0.20	0.225		
С	0 4	-	0.007	0.105	1	0.175		
c1	ს.004	0.005	0.006	0.105	0.125	0.145		
θ	0°	-	8°	0°	-	8°		
n e		0.020 BSC		(0.50 BSC	,		
D	0.488	0.492	0.496	12.40	12.50	12.60		
E	0.313	0.319	0.325	7.95	8.1	8.25		
E1	0.236	0.240	0.244	6.00	6.1	6.20		





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ORDERING INFORMATION						
Part Number Package Type Production Flow						
IMISC671DYB	48 PIN SSOP	Commercial, 0°C to +70°C				
IMISC671DTB	48 PIN TSSOP	Commercial, 0°C to +70°C				

Note: The ordering part number is formed by a combination of device number, de e revision, package style, and

screening as shown below.

Marking: Example: IMI

SC671DYB Date Code, Lot #

